

Title (en)

ADHESIVE FILM USED TO IMPLANT ELECTRIC MODULES IN A CARD BODY

Title (de)

KLEBFOLIE ZUR IMPLANTIERUNG VON ELEKTRISCHEN MODULEN IN EINEN KARTENK RPER

Title (fr)

FILM ADHESIF DESTINE A L'IMPLANTATION DE MODULES ELECTRIQUES DANS UN CORPS CARTE

Publication

**EP 1699892 A1 20060913 (DE)**

Application

**EP 04804967 A 20041221**

Priority

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- DE 10361541 A 20031223

Abstract (en)

[origin: WO2005063909A1] The invention relates to an adhesive film, comprising a blend made of synthetic rubber S1 and thermoplastics 2 which are used to stick electric modules to chip cards. According to the invention, a) the blend is separated into microphases; b) the blend has at least two softening temperatures, wherein at least one softening temperature is higher than 65 DEG C and lower than 125 DEG C; c) a G' measured according to test method A at 23 DEG C is 10<7> Pas; d) a G" measured according to test method A at 23 DEG C is 10<6 >Pas; e) and a crossover measured according to test method A is less than 125 DEG C.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

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